

u 5. (Amended) The method for packing wafers according to Claim 3, wherein a border of the aluminum bag is molded in the step of sealing the packing bag.

a 7. (Amended) A method for packing wafers comprising the steps of:
sealing a cassette in which wafers are inserted, in a polypropylene bag;
putting the cassette in a state of being sealed by the polypropylene bag, into an aluminum bag; and
sealing the aluminum bag by contacting an outer surface of the aluminum bag, opposite the polypropylene bag, so as to allow the aluminum bag to be tightly adhered along an external form of the cassette, molding a border of the aluminum bag and cutting an unnecessary border of the aluminum bag.

8. (Amended) The method for packing wafers according to Claim 7, wherein sealing the cassette in which wafers are inserted, in the polypropylene bag, comprises:
sealing the cassette in which 300 mm wafers are inserted, in the polypropylene bag.

9 11. (Amended) A method of packing a semiconductor wafer, comprising:
providing a carrying device that holds the semiconductor wafer;
inserting the carrying device into a packing bag; and
molding the packing bag by contacting an outer surface of the packing bag, opposite the carrying device, and using at least a portion of an external form of the carrying device as a guide such that a portion of the packing bag substantially conforms to the at least a portion of the external form of the carrying device.

15. (Amended) A method as recited in Claim 12, wherein inserting the carrying device into a first packing bag comprises:
inserting the carrying device into a polypropylene packing bag.

16. (Amended) A method as recited in Claim 12, wherein inserting the carrying device into the second packing bag comprises:

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inserting the carrying device into a aluminum packing bag.

20. (Amended) A method as recite in Claim 11, wherein providing the carrying device that holds the semiconductor wafer comprises:
providing the carrying device that holds a 300 mm caliber semiconductor wafer.